CLAIMS:

1. A module (3) for a data carrier (1), which module (3) includes an integrated component (4) with at least two connection contacts (5, 6) and, for each connection contact (5, 6), a connecting part (7, 8) which is electrically conductively connected to the relevant connection contact (5, 6), the connection contacts (5, 6) being constructed so as to project from the integrated component (4) and the connecting parts (7, 8) consisting of metal and being constructed so as to be plate-shaped, the connecting parts (7, 8) comprising remnants (11) of raised portions which have been formed by mechanical deformation of the connecting parts (7, 8), which remnants (11) project from the connecting parts (7, 8) in the direction of the connection contacts (5, 6).

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2. A module (3) as claimed in claim 1, in which the remnants (11) of raised portions originate from raised portions formed by stamping.

3. A module (3) as claimed in claim 1, in which the remnants (11) of raised
portions have a height of between 1.0 μm and 10 μm.

4. A module (3) as claimed in claim 1, in which the remnants (11) of raised portions have a lateral length of between 10 μ m and 50 μ m in the transitional zone to the connecting parts (7, 8).

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- 5. A module (3) as claimed in claim 1, in which a filler material (12) which encloses the connection contacts (5, 6) and the remnants (11) of raised portions is provided between the integrated component (4) and the connecting parts (7, 8).
- 6. A module (3) as claimed in claim 5, in which the filler material (12) is formed by a foil which consists of a synthetic material and can be softened at least once by heating.
 - 7. A data carrier (1) provided with a module (3) which includes an integrated component (4) with at least two connection contacts (5, 6) and, for each connection contact

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- (5, 6), a connecting part (7, 8) which is electrically conductively connected to the relevant connection contact (5, 6), the connection contacts (5, 6) being constructed so as to project from the integrated component (4) and the connecting parts (7, 8) consisting of metal and being constructed so as to be plate-shaped, the connecting parts (7, 8) comprising remnants (11) of raised portions which have been formed by mechanical deformation of the connecting parts (7, 8), which remnants (11) project from the connecting parts (7, 8) in the direction of the connection contacts (5, 6).
- 8. A data carrier (1) as claimed in claim 7, in which the remnants (11) of raised portions originate from raised portions formed by stamping.
 - 9. A data carrier (1) as claimed in claim 7, in which the remnants (11) of raised portions have a height of between 1.0 μ m and 10 μ m.
- 15 10. A data carrier (1) as claimed in claim 7, in which the remnants (11) of raised portions have a lateral length of between 10 μm and 50 μm in the transitional zone to the connecting parts (7, 8).
- 11. A data carrier (1) as claimed in claim 7, in which a filler material (12) which encloses the connection contacts (5, 6) and the remnants (11) of raised portions is provided between the integrated component (4) and the connecting parts (7, 8).
 - 12. A data carrier (1) as claimed in claim 11, in which the filler material (12) is formed by a foil which consists of a synthetic material and can be softened at least once by heating.

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